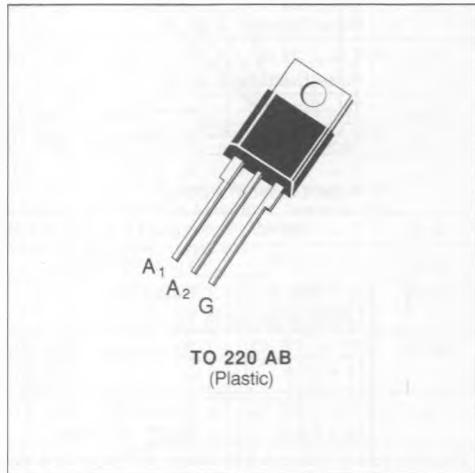


ALTERNISTORS

- $(di/dt)_c > 28 \text{ A}/\mu\text{s}$ (400 Hz)
- INSULATING VOLTAGE : 2500 V_{RMS} ($t \leq 1 \text{ ms}$ - $F = 50 \text{ Hz}$)
- UL RECOGNIZED (E81734)

APPLICATIONS

- POWER CONTROL ON INDUCTIVE LOAD (motor, transformer...)
- HIGH FREQUENCY OR HIGH $(di/dt)_c$ LEVEL CIRCUITS



DESCRIPTION

New range of solid state AC - switches with very high commutating capability.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
I _{T(RMS)}	RMS on-state Current (360° conduction angle)	T _C = 75 °C	8	A
I _{TSM}	Non Repetitive Surge Peak on-state Current	t = 10 ms	80	A
		t = 8.3 ms	85	
		t = 2.5 ms	115	
I ² t	I ² t Value for Fusing	t = 10 ms	32	A ² s
di/dt	Critical Rate of Rise of on-state Current (1)		100	A/ μ s
T _{stg} T _j	Storage and Operating Junction Temperature Range	- 40 to 150		°C
		- 40 to 110		°C

Symbol	Parameter	TXDV				Unit
		208	408	608	808	
V _{DRM}	Repetitive Peak off-state Voltage (2)	200	400	600	800	V

(1) I_G = 1 A di/dt = 1 A/ μ s

(2) T_j = 110 °C.

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
R _{th (j-a)}	Junction to Ambient		60	°C/W
R _{th (j-c) DC}	Junction to Case for DC		4	°C/W
R _{th (j-c) AC}	Junction to Case for 360° Conduction Angle (F = 50 Hz)		3	°C/W

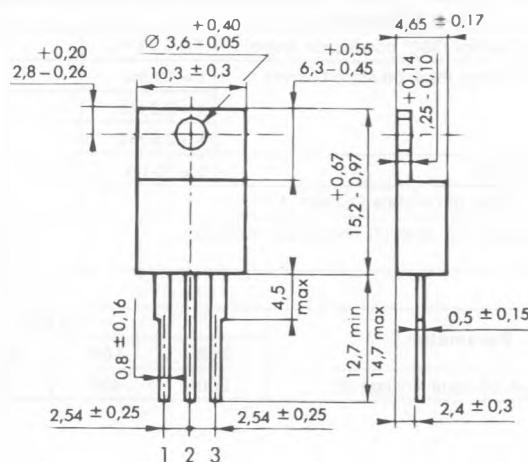
GATE CHARACTERISTICS (maximum values)

$P_{GM} = 40 \text{ W}$ ($t_p = 10 \mu\text{s}$) $I_{GM} = 4 \text{ A}$ ($t_p = 10 \mu\text{s}$)
 $P_G(\text{AV}) = 1 \text{ W}$ $V_{GM} = 16 \text{ V}$ ($t_p = 10 \mu\text{s}$)

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions	Quadrants	Min.	Typ.	Max.	Unit
I_{GT}	$T_j = 25^\circ\text{C}$ $V_D = 12 \text{ V}$ $R_L = 33 \Omega$ Pulse Duration > 20 μs	I-II-III			100	mA
V_{GT}	$T_j = 25^\circ\text{C}$ $V_D = 12 \text{ V}$ $R_L = 33 \Omega$ Pulse Duration > 20 μs	I-II-III			1.5	V
V_{GD}	$T_j = 110^\circ\text{C}$ $V_D = V_{DRM}$ $R_L = 3.3 \text{ k}\Omega$	I-II-III	0.2			V
I_H^*	$T_j = 25^\circ\text{C}$ $I_T = 500 \text{ mA}$ Gate Open	I-III			100	mA
	$T_j = 25^\circ\text{C}$ $V_D = 12 \text{ V}$ $I_G = 200 \text{ mA}$ Pulse Duration > 20 μs				200	mA
V_{TM}^*	$T_j = 25^\circ\text{C}$ $I_{TM} = 11 \text{ A}$ $t_p = 10 \text{ ms}$				1.8	V
I_{DRM}^*	$T_j = 110^\circ\text{C}$ V_{DRM} Specified				2	mA
dv/dt^*	$T_j = 110^\circ\text{C}$ Gate Open Linear Slope up to $V_D = 67\% V_{DRM}$		500			V/ μs
$(di/dt)_c^*$	$T_C = 75^\circ\text{C}$ $V_D = V_{DRM}$	$(dv/dt)_c = 200 \text{ V}/\mu\text{s}$	7			A/ μs
	$I_T = 11 \text{ A}$		28			
t_{gt}	$T_j = 25^\circ\text{C}$ $V_D = V_{DRM}$ $I_T = 11 \text{ A}$ $I_G = 0.5 \text{ A}$ $di_G/dt = 3.5 \text{ A}/\mu\text{s}$	I-II-III		2.5		μs

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

PACKAGE MECHANICAL DATA : TO 220 AB Plastic

Triac : 1 2 3 = A₁ A₂ G

Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g

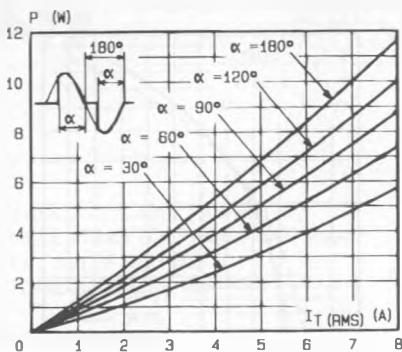


Fig.1 - Maximum mean power dissipation versus RMS on-state current.

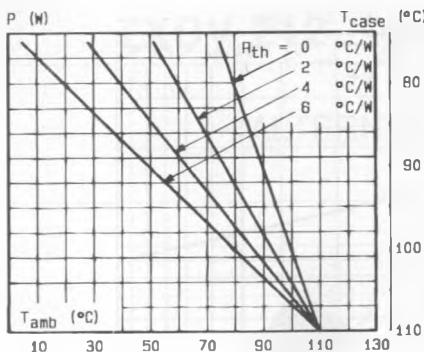


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

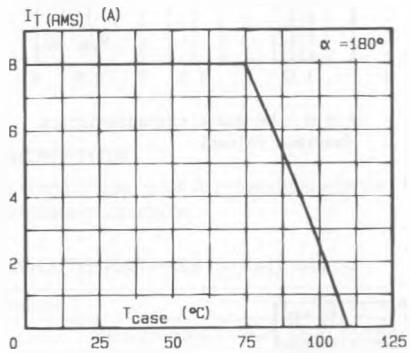


Fig.3 - RMS on-state current versus case temperature.

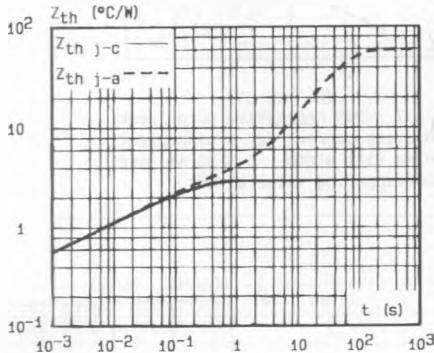


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

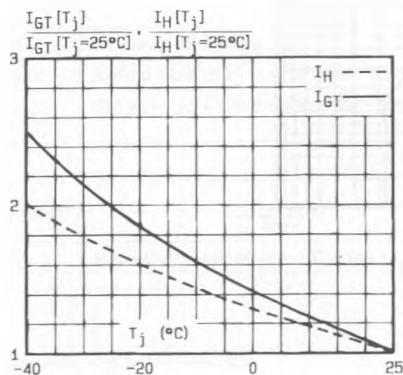


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

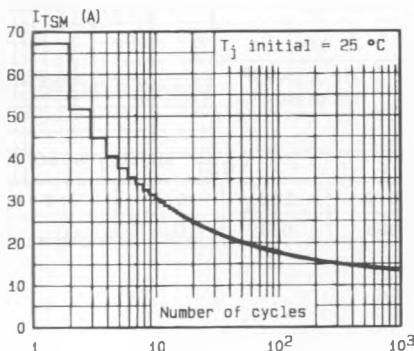


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

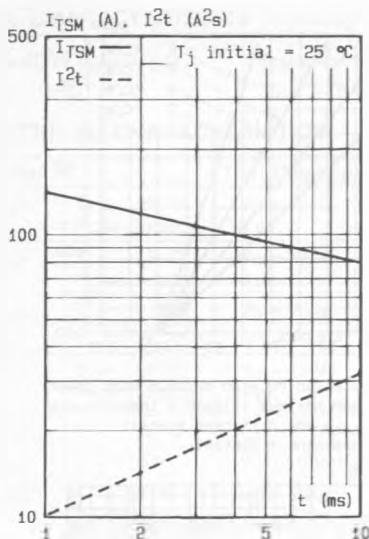


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

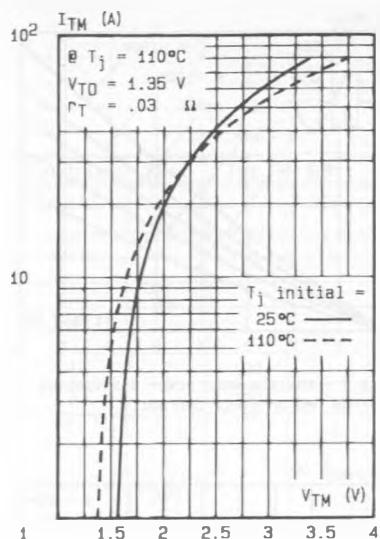


Fig.8 - Un-state characteristics (maximum values).

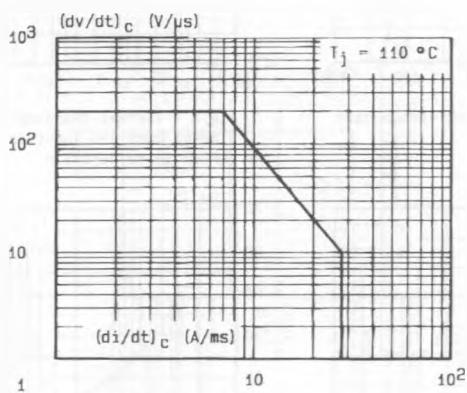


Fig.9 - Safe operating area.